

Title (en)  
MELTING VESSELS PROVIDED WITH A COOLED BOTTOM ELECTRODE

Title (de)  
MIT EINER GEKÜHLTEN BODENELEKTRODE VERSEHENE SCHMELZGEFÄSSE

Title (fr)  
RECIPIENTS DE FUSION DOTES D'UNE ELECTRODE DE MASSE REFROIDIE

Publication  
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Application  
**EP 00935164 A 20000603**

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Abstract (en)  
[origin: DE19925554A1] The aim of the invention is to improve the cooling of the bottom electrodes (1) of metallurgical melting vessels. To this end, a cooling plate (5) is situated beneath the support plate (2) on which the contact elements (3) are supported. The cooling plate is set apart from the support plate. This forms a cooling chamber (4) through which a cooling medium flows, the cooling effect of said medium being reinforced by cooling ribs (6). Said cooling ribs are situated in the cooling chamber (4) and are welded to the support plate (2) and preferably, also to the cooling plate (5).

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